



Features 特性

- High Thermal Conductivity 高导热
- Low Compression Stress 低应力
- High Reliability 高可靠性
- Automatic Dispensing 自动化点胶

Applications 产品应用

- Consumer Electronics 消费电子
- Communication Equipment 通讯设备
- Power Supply Controller 电源控制系统
- Smart Wearable Product 智能穿戴产品

Thermal TG1000C 是一种具有高导热，低压缩应力和优异可靠性的单组份导热凝胶。其具有良好的弥合公差能力，适用于自动化点胶等应用场景。该产品可在常温下短期储存，并在高温下固化形成具有弹性的垫片。

Thermal TG1000C is a kind of one-component thermal conductive gel with high thermal conductivity, low compression stress and excellent reliability performance. The material provides good gap filling ability and could be used for automatic dispensing. This product can be stored at RT for short-term and cured at elevated temperature to form elastic pad.

| Property 特性 | Typical Value 典型值 | Unit 单位 | Test Method 测试方法 |
|-------------------------------------|--|-------------------|-----------------------|
| Composition 主要成分 | Silicone Filled with Thermal Powder 硅胶&导热粉体 | — | — |
| Color 颜色 | Red 红色 | — | Visual 目视 |
| Thermal Conductivity 导热系数 | 10.0 | W/m·K | ASTM D5470 |
| Flow Rate 流速 | 25 | g/min | 30cc EFD, 90Psi |
| Density 密度 | 3.25 | g/cm ³ | ASTM D792 |
| Hardness 硬度 (Shore 00) | 75 | — | ASTM D2240 |
| Cure Time 固化时间 | 60@85°C 30@100°C | min | — |
| Temperature Range 耐温范围 | -40 - 150 | °C | — |
| Breakdown Voltage 击穿强度 | 8.0 | KV/mm | ASTM D149 |
| Flame Rating 阻燃等级 | V-0 | — | UL 94 |
| RoHS Compliance 合规性 | YES | — | — |
| Shelf Life 保存期 | 6 | Month | ≤-10°C, 未启封 |
| | ≥7 | Day | 25±5°C, ≤50% RH, 密封包装 |

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

此技术资料里所有陈述的技术信息，全部是基于本公司对自身产品在经过严格的测试评估后，证明各项技术参数指标是值得信赖的前提下编写的。在您使用我们公司产品之前，请充分评估该产品是否符合您的使用需求，您需要承担使用的全部风险和责任。